ETX-700

AMD LX800/900 + CS5536 ETX Board

Thermal Image Analysis Report

Report NO:08E080001

Release Date: January 11, 2008

2008/01/11 *Wenyuan Yang* *Kevin Hsu*

Issue Stamp	Manager	Test Engineer

Thermal Image Analysis

Ⅰ. Model Name: ETX-700 B0.2

Ⅱ. Description: AMD LX800/900 + CS5536 ETX Board

Ⅲ. Date: January 11, 2008

Ⅳ. Measure Site: AAEON QE Dept.

Ⅴ. Issued by : Kevin Hsu

Ⅵ.Equipment:

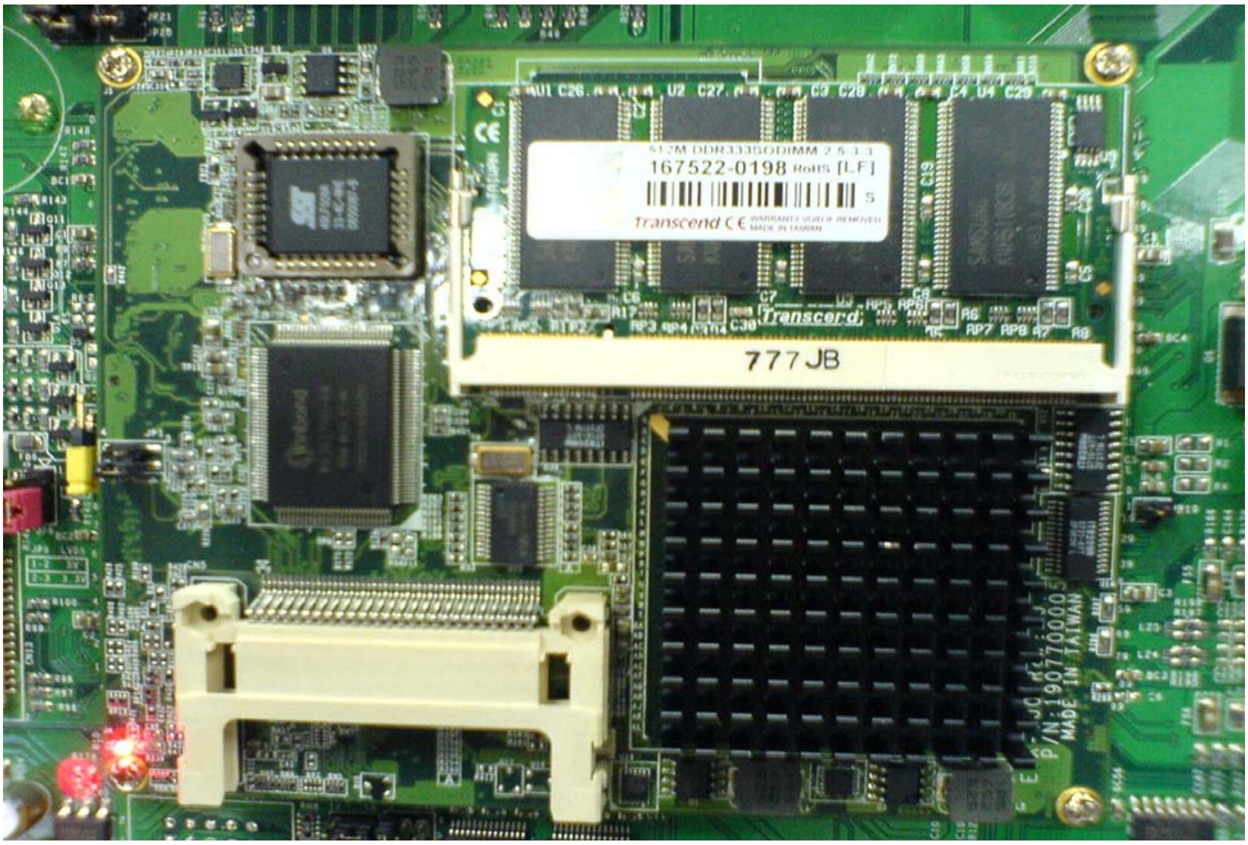
TVS-100 series by NIPPON AVIONICS CO., LTD.

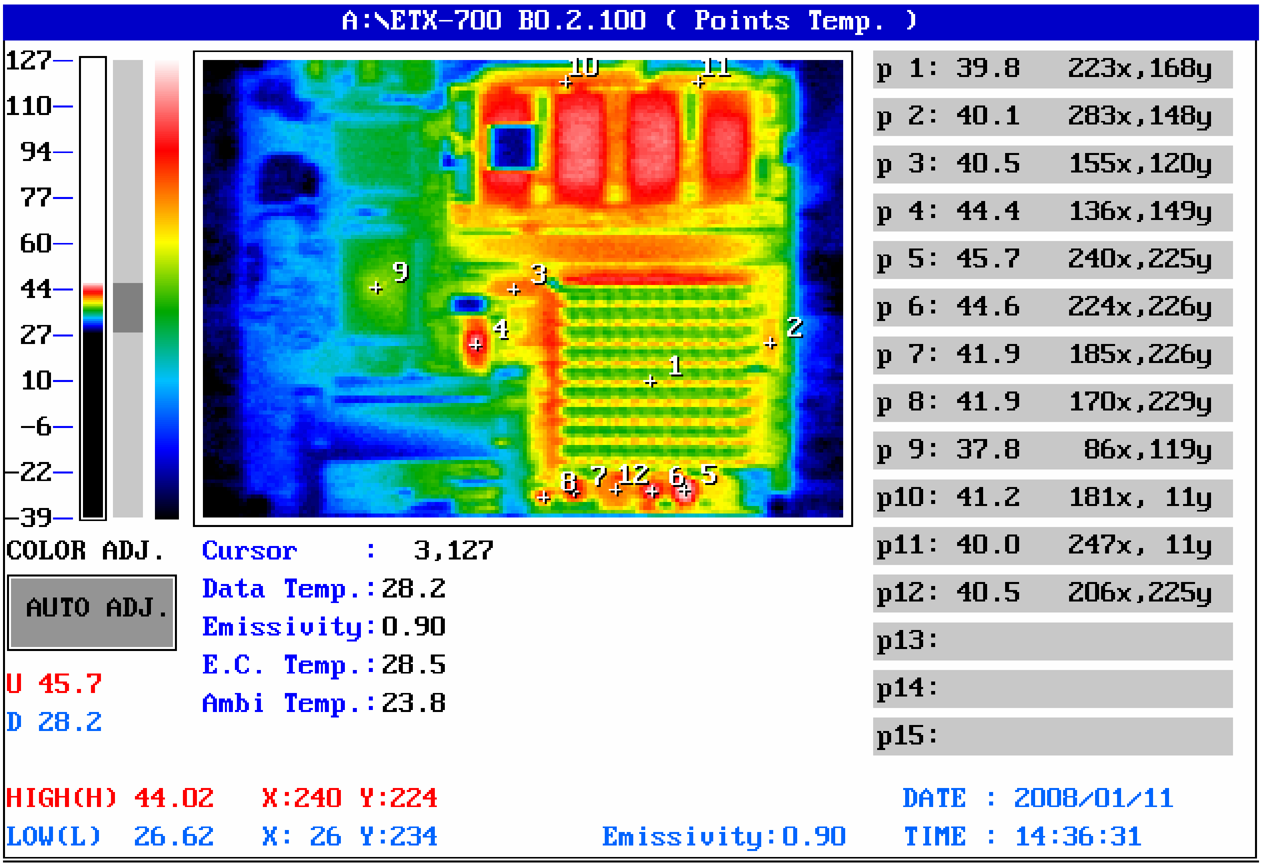
Ⅶ. Simulation Environment:

- **Temperature: Component Side : 23.8℃**
- **CPU : AMD LX-800 500MHz**
- **RAM : DSL DDR 333 512MB (SAMSUNG K4H510838D-UCCC)**
- **BIOS : ETX-700 BIOS RevB 1.0 (11/19/2007)**
- **CF Card : N/A**
- **HDD: Seagate ST340014A Barracuda 7200.7 40Gbytes HDD**
- **Application Software: Run Prime95 under Windows XP Professional V2002 Service Pack 2**
- **Take Picture Time: After Power on 2 hours.**

Temperature Profile Test:

Component Side :





A:\ETX-700 B0.2.100 (Points Temp.)

p 1:	39.8	223x,168y
p 2:	40.1	283x,148y
p 3:	40.5	155x,120y
p 4:	44.4	136x,149y
p 5:	45.7	240x,225y
p 6:	44.6	224x,226y
p 7:	41.9	185x,226y
p 8:	41.9	170x,229y
p 9:	37.8	86x,119y
p10:	41.2	181x, 11y
p11:	40.0	247x, 11y
p12:	40.5	206x,225y
p13:		
p14:		
p15:		

Cursor : 3,127
Data Temp.:28.2
Emissivity:0.90
E.C. Temp.:28.5
Ambi Temp.:23.8

U 45.7
D 28.2

HIGH(H) 44.02 X:240 Y:224
LOW(L) 26.62 X: 26 Y:234
Emissivity:0.90
DATE : 2008/01/11
TIME : 14:36:31

Point	Position	Describe	Tc (℃)	Tm (23.8℃)	Tm (60℃)	Note
1	U12	(TF)AMD CPU.BGU481.LX-800.500MHz.1.25V.AMD. ALXD800EEXJ2VD;EE-A061318;14S4800002;TWN	0~85	39.8	76	
2	U16	(TF)IC.SMD SSOP 28Pin.Extended PCI Arbiter Buffer.ITE.IT8209R;EE-A050147;14S4820900;TWN	-30~100	40.1	76.3	
3	U39	(TF)IC.SMD.SOP 16Pin PCI Arbiter.ITE.IT8208M;EE-A031200;14S9820800;TWN	-30~100	40.5	76.7	
4	U22	(TF)IC.SMD.SSOP28.Clock Generator.ICS.MK1491-09FLN;EE-A051233;14S3149103;TWN	-30~100	44.4	80.6	
5	Q3	(TF)Dual N-Channel.SO-8.SMD.Vds=30V.Ids=6A.Rds=21/27mohm. Vgs=10/4.5V.ANPEC.APM7313KC-TRL;EE-A060563;1315731310;TWN	-5~130	45.7	81.9	
6	U26	(TF)IC.SMD MLPD-10.PWM BUCK CONTROLLER.IR.IR3624MTRPBF;EE-A061341;14S2362400;TWN	-15~125	44.6	80.8	
7	Q5	(TF)Dual N-Channel.SO-8.SMD.Vds=30V.Ids=6A.Rds=21/27mohm. Vgs=10/4.5V.ANPEC.APM7313KC-TRL;EE-A060563;1315731310;TWN	-5~130	41.9	78.1	
8	U29	(TF)IC.SMD MLPD-10.PWM BUCK CONTROLLER.IR.IR3624MTRPBF;EE-A061341;14S2362400;TWN	-15~125	41.9	78.1	
9	U20	(TF)IC.SMD.PQFP 128Pin.LPC Super I/O.Winbond.W83627HG-AW A version;EE-A051465;14S4362704;TWN	-30~100	37.8	74	
10	U15	(TF)IC.SMD 208PBGA.I/O Companion.Multi-Function South Bridge.AMD.CS5536AD;EE-A061313;14S4553600;TWN	0~85	41.2	77.4	
11	U25	(TF)IC.SMD TFBGA.160P.PCI to ISA Bridge Chip.ITE.IT8888G-L;EE-A051091;14S4888801;TWN	-30~100	40.0	76.2	
12	L4	(TF)COIL.1.5uH.Irms=9A.Isat=18A.20%.SMD(7.3x6.8x3.0).2pin. RDC=15m Ohm.GOTREND.GSTC063P-1R5MN;EE-A061612; 121110156A;TWN	-55~125	40.5	76.7	
13						
14						
15						

Tm (Measured operation temperature) must be less than Tc (Specified case temperature) +5 degree C

Any Tm value showed in red words which meaning the value is over the Tc+ 5 degree C of this device specification